

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A semiconductor package comprising:
 - a chip carrier including a grounded pad on a first side of said chip carrier;
 - a semiconductor chip coupled to said first side of said chip carrier;
 - a conductive lid thermally coupled to said semiconductor chip, wherein the entire length of said conductive lid is substantially parallel with said first side of said chip carrier, and wherein an end of said conductive lid extends beyond a side of said semiconductor chip;
 - and
 - ~~a picked and placed conductive block~~ a plurality of discrete conductive structures located upon said chip carrier and physically spaced apart from each other, each of said conductive structures having about the same dimensions as a discrete chip component, wherein ~~said conductive block~~ at least one of said conductive structures is electrically coupled to said grounded pad and to said conductive lid, and further wherein:
 - each of said conductive structures located beyond said side of said semiconductor chip and within said end of said conductive lid that extends beyond said semiconductor chip;
 - and
 - each of said conductive structures have a side coupled by an adhesive material to said chip carrier and an opposite side coupled by another adhesive material to a portion of said conductive lid that extends beyond said semiconductor chip, wherein a gap between said chip carrier and said portion of said conductive lid that extends beyond said semiconductor chip is substantially filled by only said conductive structures and said adhesive materials in regions where said conductive structures are located, while a gap remains between said chip carrier and said portion of said conductive lid that extends beyond said semiconductor chip in regions where said conductive structures are not located.
2. (Currently Amended) The semiconductor package of claim 1 wherein a solder connects ~~said conductive block~~ at least one of said conductive structures and said grounded pad.
3. (Currently Amended) The semiconductor package according to claim 1 wherein said

~~conductive block~~ at least one of said conductive structures is electrically coupled to said grounded pad with an electrically conductive adhesive material.

4. (Currently Amended) The semiconductor package according to claim 1 wherein said ~~conductive block is~~ structures are electrically coupled to said conductive lid with an electrically conductive adhesive material.
5. (Currently Amended) The semiconductor package according to claim 1 wherein said ~~conductive block is~~ structures are coupled to said chip carrier using an electrically insulative adhesive material.
6. (Currently Amended) The semiconductor package according to claim 1 wherein said ~~conductive block is~~ structures are coupled to said chip carrier using a thermally conductive adhesive material.

Claims 7-9. (Canceled)

10. (Currently Amended) The semiconductor package according to claim 1 wherein
a solder couples said at least one of said conductive block structures to said grounded pad;
an electrically conductive adhesive material couples said ~~conductive block~~ structures to said conductive lid; and
an electrically insulative adhesive material couples said ~~conductive block~~ structures to said chip carrier.

Claims 11 – 22. (Canceled)

23. (Currently Amended) The semiconductor package of claim 1 wherein said ~~conductive block is~~ structures are located on said first side of said chip carrier.

24. (Canceled)

25. (Currently Amended) The semiconductor package of claim 1 wherein each of said conductive ~~block occupies~~ structures occupy a substantial amount of a gap between a lower surface of said conductive lid and an upper surface of said chip carrier.

26. (Currently Amended) The semiconductor package of claim 25 wherein each of said conductive ~~block occupies~~ structures occupy about 90% of said gap.

Claims 27-33. (Canceled)

34. (New) The semiconductor package of claim 1, wherein no part of said conductive structures are aligned with said end of said conductive lid.

35. (New) The semiconductor package of claim 1, wherein, between said chip carrier and said conductive lid, only said conductive structures and said adhesive materials physically support portions of said conductive lid that extend beyond said semiconductor chip.

36. (New) The semiconductor package of claim 1, wherein said conductive structures comprise blocks.

37. (New) The semiconductor package of claim 1, wherein said conductive structures comprise springs.

38. (New) The semiconductor package of claim 1, wherein said conductive structures comprise surface mount technology (SMT) discrete components.